onsemi

Final Product/Process Change Notification

Document #:FPCN25224X
Issue Date:05 Jul 2023

Title of Change:	Qualification of onsemi Aizu Japan as wafer Fab for ONC25BCD Technology for select products in NCS20071 family
Proposed First Ship date:	12 Oct 2023 or earlier if approved by customer
Contact Information:	Contact your local onsemi Sales Office or Adrian.Croitoru@onsemi.com
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Additional Reliability Data:	Contact your local onsemi Sales Office or Vladislav.Hrachovec@onsemi.com
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com
Marking of Parts/ Traceability of Change:	Custom source information will be updated on product label. Product traceability will be identified by encoded date code.
Change Category:	Wafer Fab Change
Change Sub-Category(s):	Manufacturing Site Addition

Sites Affected:

onsemi Sites	**External Foundry/Subcon Sites**
onsemi Aizu, Japan	None

Description and Purpose:

onsemi would like to inform its customers of qualification of an additional wafer fabrication facility for ONC25 technology at onsemi Aizu, Japan for the devices listed in this FPCN. All products listed here will be dual sourced from onsemi Gresham and onsemi Aizu.

There is no change to the orderable part number.

There is no product marking change as a result of this notification.

No changes to part specification or datasheet are anticipated.

NCS20071 FAMILY – TSOP5 and SOT553 packages	From	To
Wafer Fab	onsemi, Gresham, Oregon (US)	onsemi, Gresham, Oregon (US) onsemi, Aizu (Japan)

Reliability Data Summary:

QV DEVICE NAME: NCS20072DR2G
RMS: O86311
PACKAGE: SOIC-8

Test	Specification	Condition	Interval	Results
High Temperature Operating Life	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008 hrs	0/77
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hrs	0/77
Early Life Failure Rate	JESD22-A108	Ta=125°C, 100 % max rated Vcc	48 hrs	0/800
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260°C, Pre TC, uHAST, HAST for surface mount pkgs only		0/all
Temperature Cycling	JESD22-A104	Ta= -55°C to +150°C	1000 cyc	0/77
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/77
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/77

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

***Note:** Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.*

Part Number	Qualification Vehicle
NCS20071XV53T2G	NCS20072DR2G
NCS20071SN2T1G	NCS20072DR2G

DIKG: DIGI-KEY

Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
NCS20071XV53T2G		NCS20072DR2G	NA	
NCS20071SN2T1G		NCS20072DR2G	NA	